

# E4MS025120U2

Silicon Carbide Power MOSFET  
Switching Optimized 1200V 25mΩ Automotive  
N-Channel Enhancement Mode

## Features

- Industry compatible drive voltage 15V...18V/-5V...0V
- Soft body diode with low Vds overshoot and ringing
- Low Rds(on) at high operating temperatures
- Improved device capacitances ratio (Ciss/Crss)
- High transient voltage robustness with improved lifetime
- Halogen free, RoHS compliant
- Automotive Qualified (AEC-Q101) and PPAP Capable

## Benefits

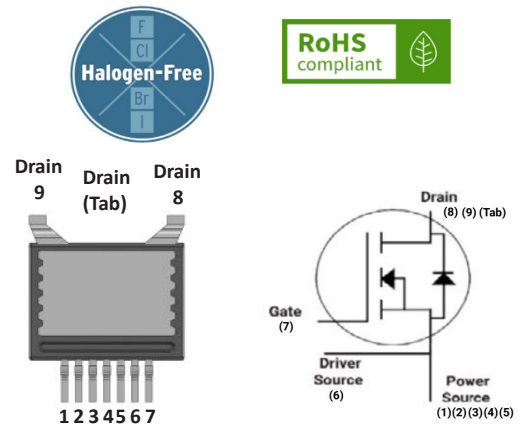
- Higher efficiency with lower switching losses and EMI
- Faster switching operation enabling high power density
- Enables system level price performance optimization
- Reduction in system level cooling requirements

## Typical Applications

- Motor Control
- EV On Board Battery Chargers (OBC)
- Automotive DC/DC Converters for EV/HEV



## Package



Orderable Part number	Package type	Marking
E4MS025120U2-TR	TO-263-7XL	E4MS025120U2

## Key Parameters

Parameter	Symbol	Min.	Typ.	Max	Unit	Conditions	Note
Drain - Source Voltage	$V_{DS}$			1200	V		
Maximum Gate - Source Voltage	$V_{GS(max)}$	-10		+23			
DC Continuous Drain Current	$I_D$			82	A	$V_{GS} = 18V, T_C = 25^\circ C, T_J \leq 175^\circ C$	Note 1
				61		$V_{GS} = 18V, T_C = 100^\circ C, T_J \leq 175^\circ C$	
Pulsed Drain Current	$I_{DM}$			274		$t_{Pmax}$ limited by $T_{Jmax}$ $V_{GS} = 18V, T_C = 25^\circ C$	
Power Dissipation	$P_D$			350	W	$T_C = 25^\circ C, T_J = 175^\circ C$	Note 2
Operating Junction and Storage Temperature	$T_J, T_{stg}$	-55		+175	$^\circ C$		
Solder Temperature	$T_L$			260			

Note (1): Current limit calculated by  $I_{D(max)} = \sqrt{(P_D / R_{DS(typ)}) (T_{J(max)} - T_{D(max)})}$

Note (2):  $P_D = (T_J - T_C) / R_{th(JC, max)}$


**Electrical Characteristics** ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	1200			V	$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	
$V_{GS(th)}$	Gate Threshold Voltage	2	2.6	3.9	V	$V_{DS} = V_{GS}, I_D = 10.8\text{ mA}$	Fig. 11
			2.0		V	$V_{DS} = V_{GS}, I_D = 10.8\text{ mA}, T_J = 175^\circ\text{C}$	
$I_{DSS}$	Zero Gate Voltage Drain Current		1	50	$\mu\text{A}$	$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}$	
$I_{GSS}$	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 18\text{ V}, V_{DS} = 0\text{ V}$	
$V_{GS(op)}$	Recommended Turn on Gate-Source Voltage		+15...+18		V		Refer to PRD-09634
	Recommended Turn off Gate-Source Voltage		-5...0				
$R_{DS(on)}$	Drain-Source On-State Resistance		25	33	m $\Omega$	$V_{GS} = 18\text{ V}, I_D = 39.2\text{ A}$	Fig. 4, 5, 6
			47			$V_{GS} = 18\text{ V}, I_D = 39.2\text{ A}, T_J = 175^\circ\text{C}$	
			28			$V_{GS} = 15\text{ V}, I_D = 39.2\text{ A}$	
$g_{fs}$	Transconductance		28		S	$V_{DS} = 20\text{ V}, I_D = 39.2\text{ A}, T_J = 25^\circ\text{C}$	Fig. 7
			27			$V_{DS} = 20\text{ V}, I_D = 39.2\text{ A}, T_J = 175^\circ\text{C}$	
$R_{DS(on)Tempco}$	On resistance temperature coefficient		1.88			$V_{GS} = 18\text{ V}, I_D = 39.2\text{ A}$	Note 3
$C_{iss}$	Input Capacitance		3087		pF	$V_{GS} = 0\text{ V}, V_{DS} = 1000\text{ V}$ $f = 100\text{ kHz}$ $V_{AC} = 25\text{ mV}$	Fig. 17, 18
$C_{oss}$	Output Capacitance		103				
$C_{rss}$	Reverse Transfer Capacitance		4.7				
$C_{iss}/C_{rss}$	Capacitance Ratio		630				Note 4
$E_{oss}$	$C_{oss}$ Stored Energy		63		$\mu\text{J}$		Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		145		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0...800\text{ V}$	
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		238				
$E_{on}$	Turn-On Switching Energy (Body Diode FWD) $T_J = 25^\circ\text{C}$ $T_J = 175^\circ\text{C}$		394 470		$\mu\text{J}$	$V_{DS} = 800\text{ V}, V_{GS} = -4\text{ V}/18\text{ V}, I_D = 39.2\text{ A},$ $R_{G(ext)} = 1\text{ }\Omega, L_\sigma = 25\text{ nH}$	Fig. 26, 29, 31
	Turn-Off Switching Energy (Body Diode FWD) $T_J = 25^\circ\text{C}$ $T_J = 175^\circ\text{C}$		57 64				Fig. 26, 29, 32
$t_{d(on)}$	Turn-On Delay Time		12		ns	$V_{DD} = 800\text{ V}, V_{GS} = -4\text{ V}/18\text{ V}$ $I_D = 39.2\text{ A}, R_{G(ext)} = 1\text{ }\Omega,$ Timing relative to $V_{DS}$ Inductive load	Fig. 27, 28
$t_r$	Rise Time		4				
$t_{d(off)}$	Turn-Off Delay Time		36				
$t_f$	Fall Time		11				
$R_{G(int)}$	Internal Gate Resistance		2.6		$\Omega$	$f = 1\text{ MHz}$	
$Q_{gs}$	Gate to Source Charge		35		nC	$V_{DS} = 800\text{ V}, V_{GS} = -4\text{ V}/18\text{ V}$ $I_D = 39.2\text{ A}, T_J = 25^\circ\text{C}$ Per IEC60747-8-4 pg 21	Fig. 12
$Q_{gd}$	Gate to Drain Charge		30				
$Q_g$	Total Gate Charge		125				

Note (3):  $R_{DS(on)Tempco}$  refers to  $R_{DS(on)}$  at  $175^\circ\text{C}$  /  $R_{DS(on)}$  at  $25^\circ\text{C}$ , E4MS 1200V product family value

Note (4): Capacitance ratio is a FOM for Partial turn-on immunity PRD-06933, E4MS 1200V product family value

$C_{o(er)}$ , a lumped capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{ds}$  is rising from 0 to 800V

$C_{o(tr)}$ , a lumped capacitance that gives the same charging time as  $C_{oss}$  while  $V_{ds}$  is rising from 0 to 800V



Reverse Diode Characteristics (T<sub>c</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V <sub>SD</sub>	Diode Forward Voltage	5.1		V	V <sub>GS</sub> = -4 V, I <sub>SD</sub> = 19.6 A, T <sub>j</sub> = 25 °C	Fig. 8, 9, 10
		4.6		V	V <sub>GS</sub> = -4 V, I <sub>SD</sub> = 19.6 A, T <sub>j</sub> = 175 °C	
I <sub>S</sub>	Continuous Diode Forward Current		56	A	V <sub>GS</sub> = -4 V, T <sub>c</sub> = 25°C	
I <sub>SM</sub>	Diode Pulse Current		274	A	V <sub>GS</sub> = -4 V, pulse width t <sub>p</sub> limited by T <sub>jmax</sub>	
t <sub>rr</sub>	Reverse Recovery Time	14		ns	V <sub>GS</sub> = -4 V, I <sub>S</sub> = 39.2 A, V <sub>SD</sub> = 800V T <sub>j</sub> = 175°C, diF/dt = 13.8 A/ns	
Q <sub>rr</sub>	Reverse Recovery Charge	742		nC		
I <sub>RRM</sub>	Peak Reverse Recovery current	94		A		
E <sub>RR</sub>	Reverse recovery Energy			μJ	V <sub>DS</sub> = 800 V, I <sub>D</sub> = 39.2 A,	
	T <sub>j</sub> = 25C	102			V <sub>GS</sub> = -4V/18V, R <sub>Gi(on)</sub> = 1 Ω, Lσ = 25nH	
	T <sub>j</sub> = 175C	256				

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
R <sub>θJC</sub>	Thermal Resistance from Junction to Case	0.33	0.43	°C/W		



Typical Performance

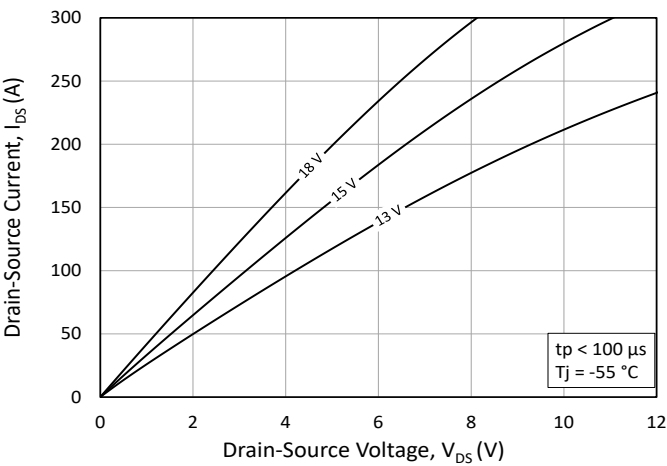


Figure 1. Output Characteristics  $T_j = -55^{\circ}\text{C}$

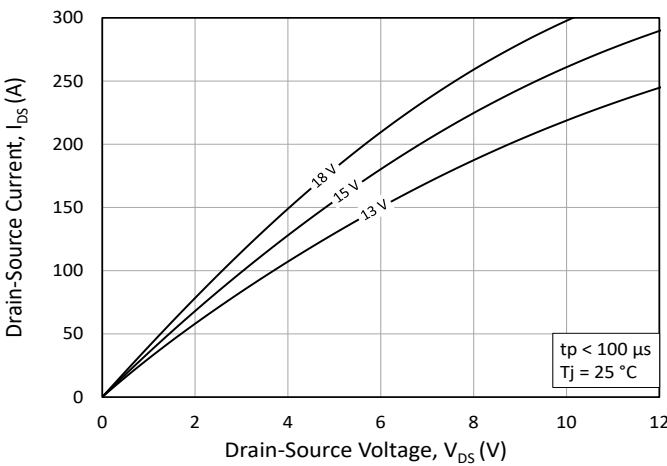


Figure 2. Output Characteristics  $T_j = 25^{\circ}\text{C}$

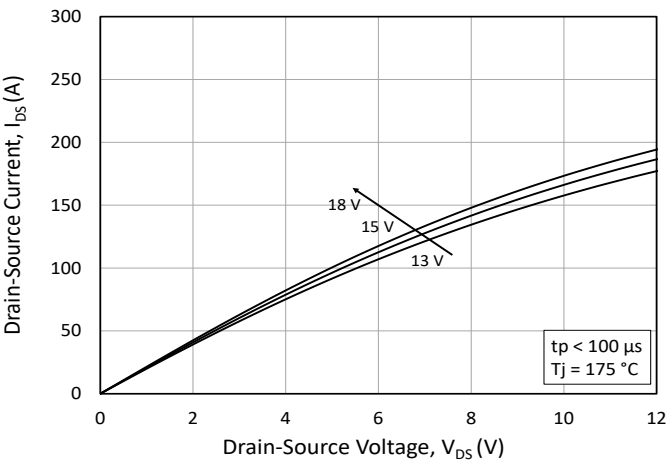


Figure 3. Output Characteristics  $T_j = 175^{\circ}\text{C}$

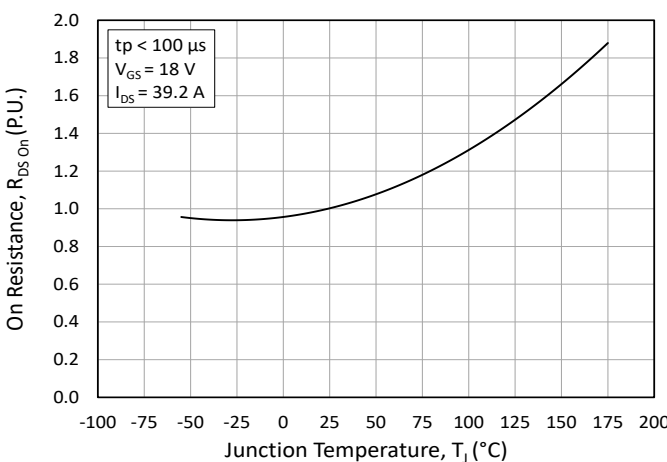


Figure 4. Normalized On-Resistance vs. Temperature

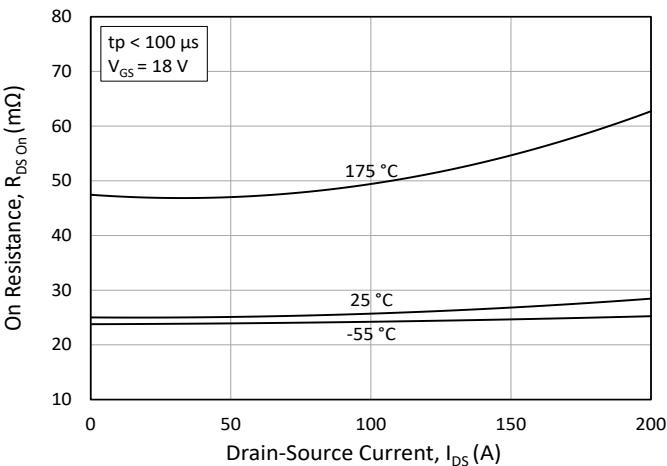


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

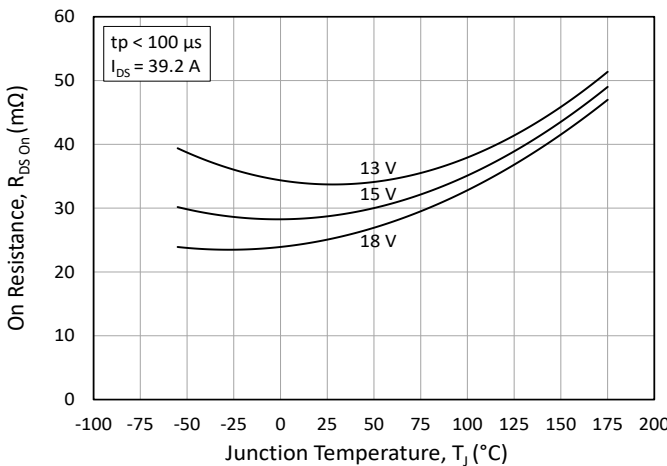


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage





Typical Performance

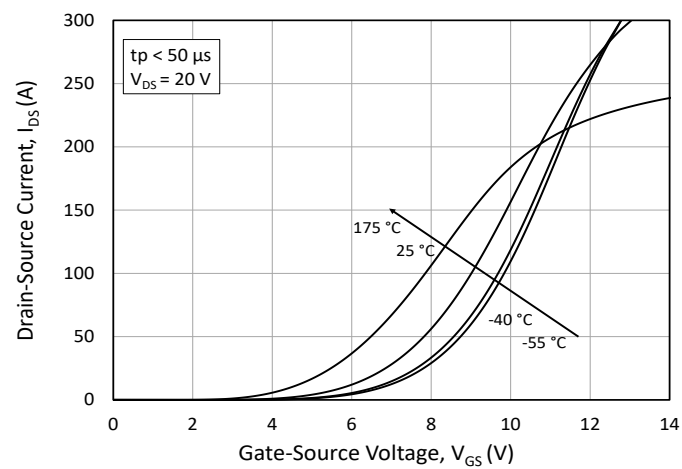


Figure 7. Transfer Characteristic for Various Junction Temperatures

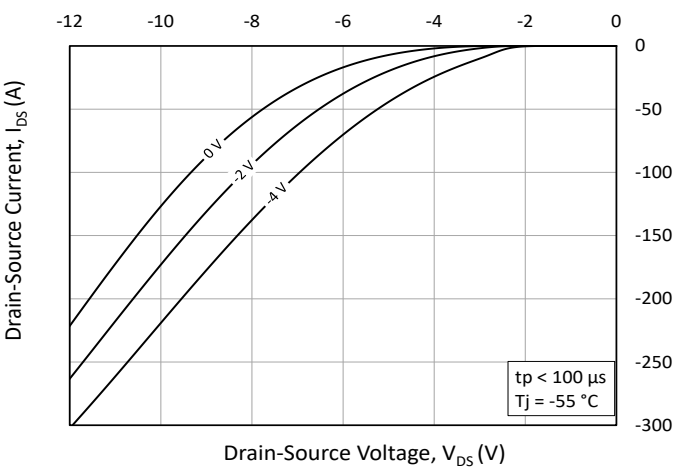


Figure 8. Body Diode Characteristic at  $-55\text{ }^{\circ}\text{C}$

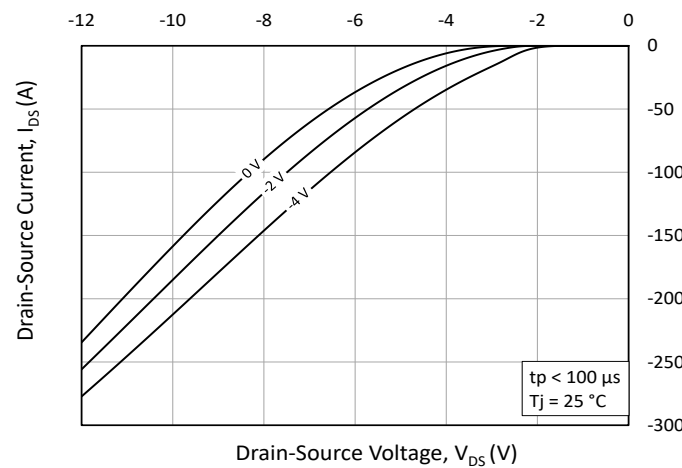


Figure 9. Body Diode Characteristic at  $25\text{ }^{\circ}\text{C}$

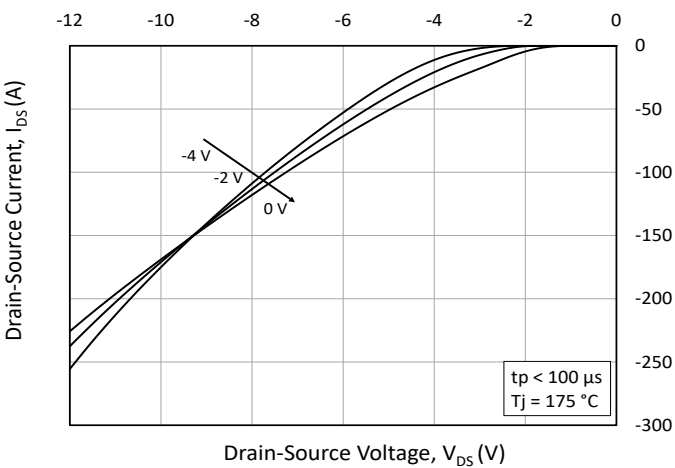


Figure 10. Body Diode Characteristic at  $175\text{ }^{\circ}\text{C}$

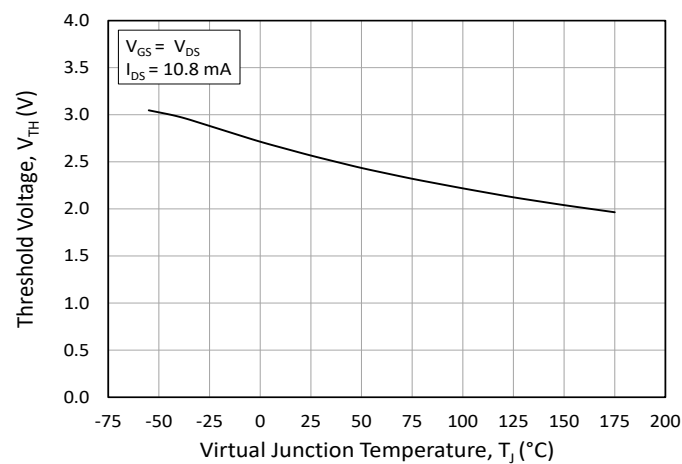


Figure 11. Threshold Voltage vs. Temperature

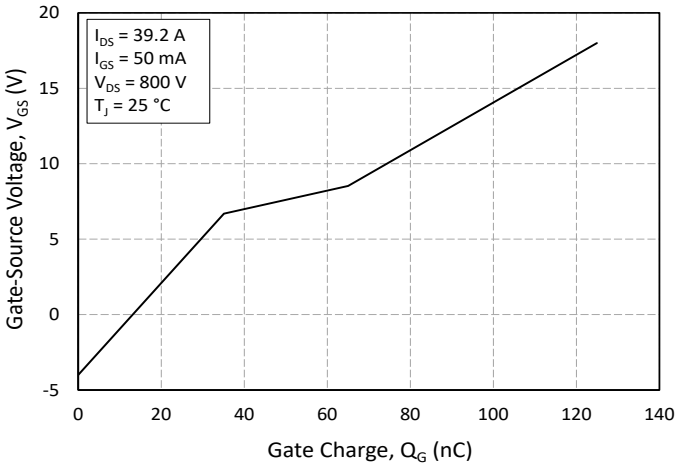


Figure 12. Gate Charge Characteristics

## Typical Performance

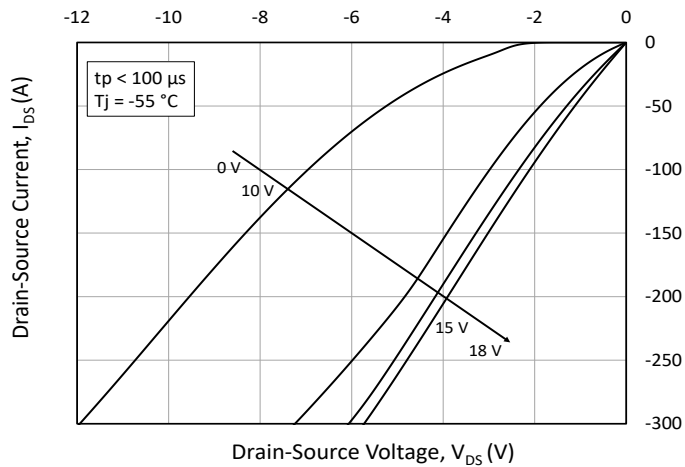


Figure 13. 3rd Quadrant Characteristic at -55°C

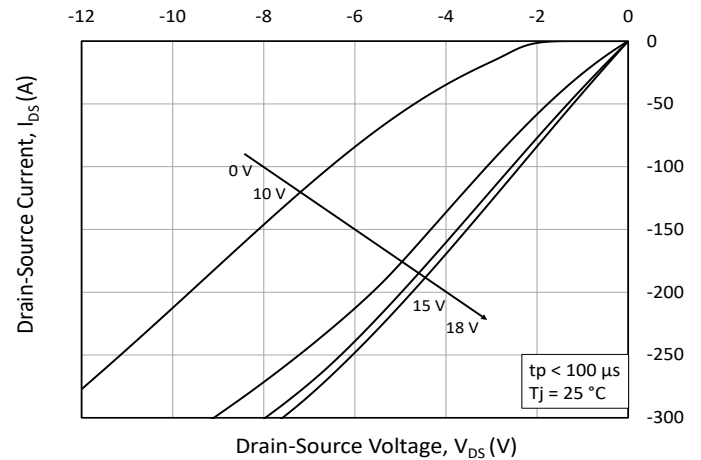


Figure 14. 3rd Quadrant Characteristic at 25°C

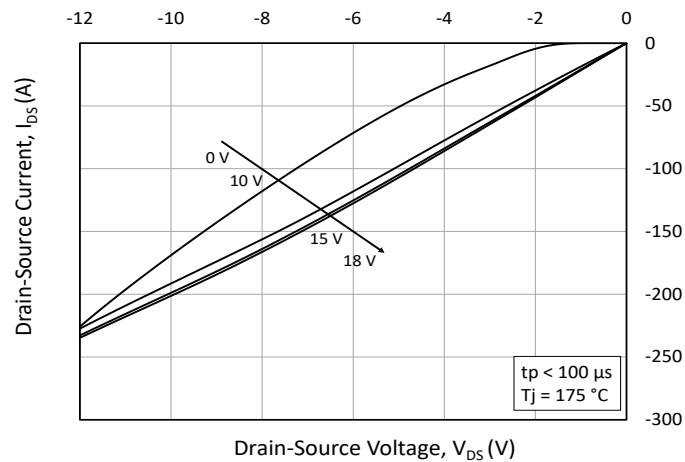


Figure 15. 3rd Quadrant Characteristic at 175°C

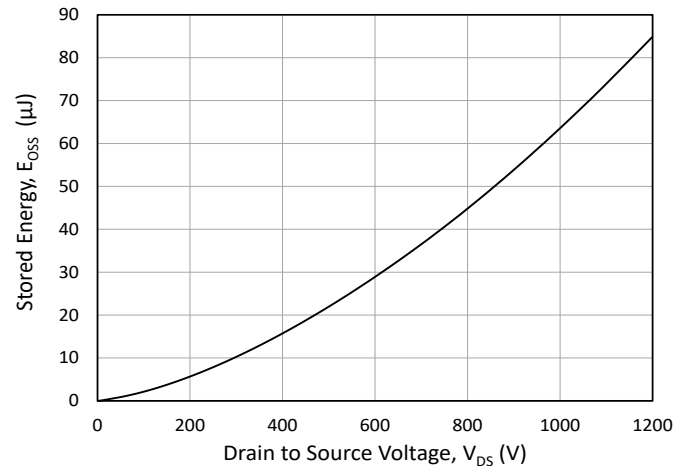


Figure 16. Output Capacitor Stored Energy

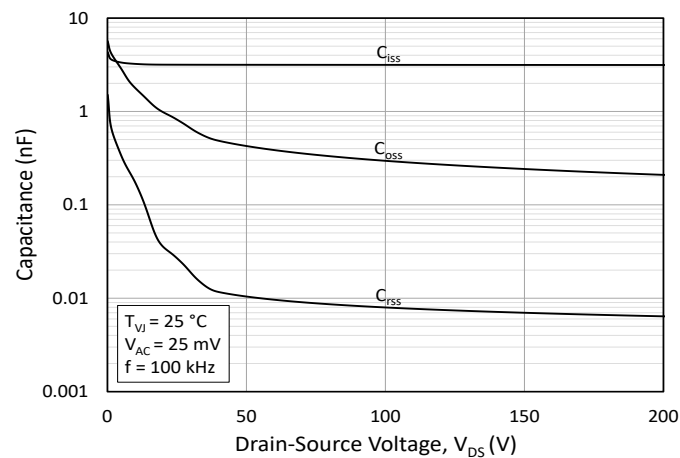


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200 V)

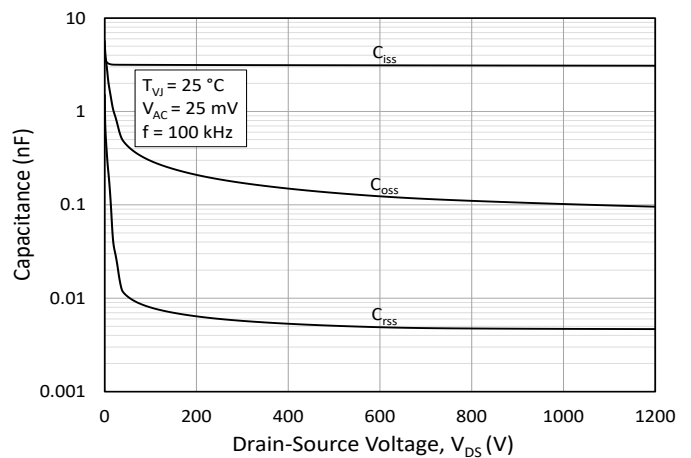


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1200 V)

## Typical Performance

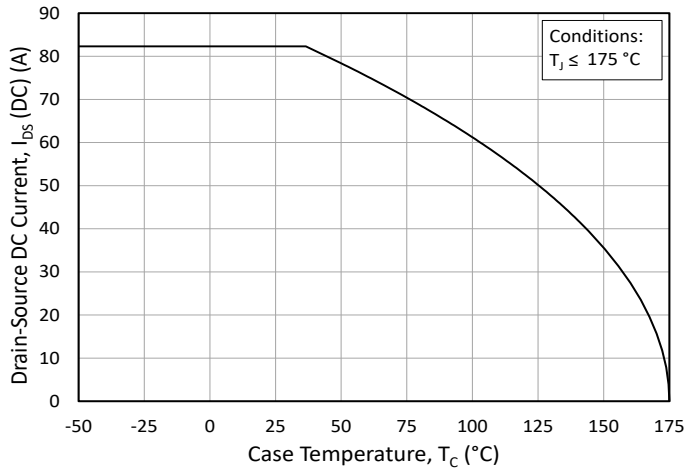


Figure 19. Continuous Drain Current Derating vs. Case Temperature

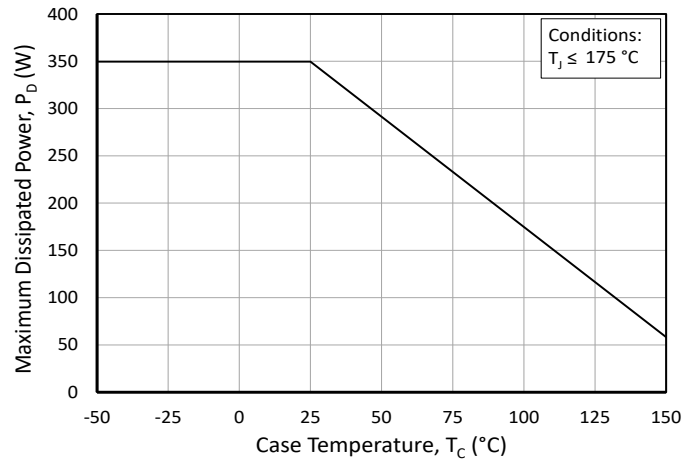


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

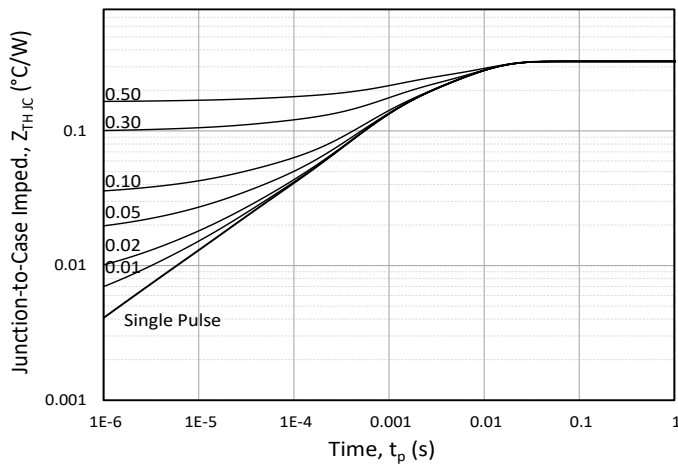


Figure 21. Transient Thermal Impedance (Junction - Case)

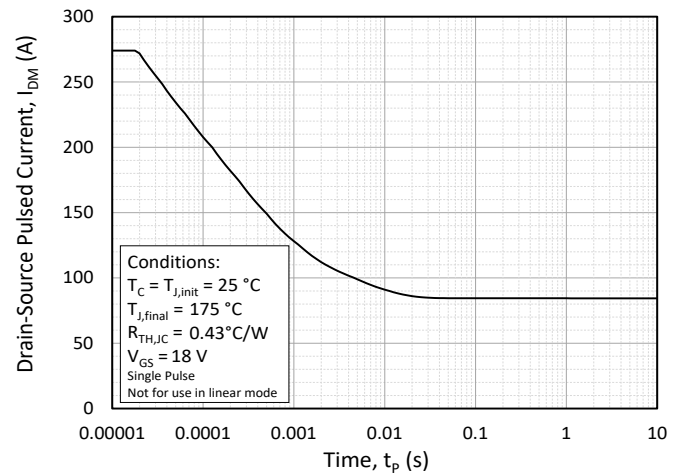
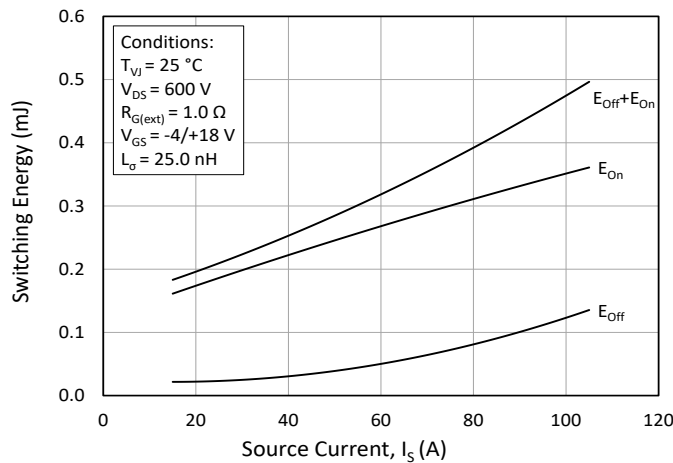
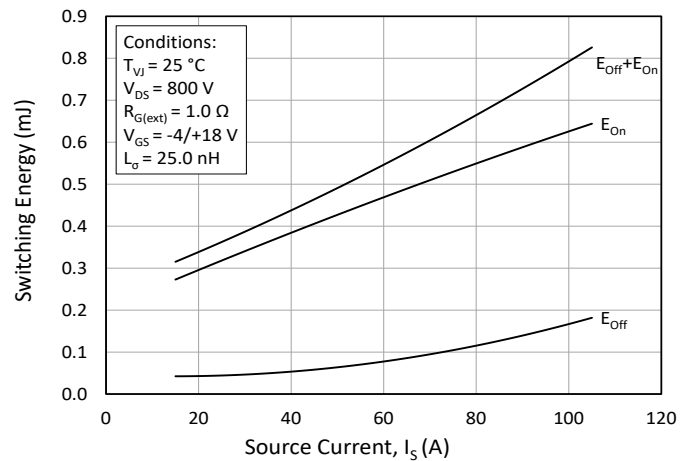


Figure 22. Safe Operating Area

Figure 23. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 600$  V)Figure 24. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 800$  V)

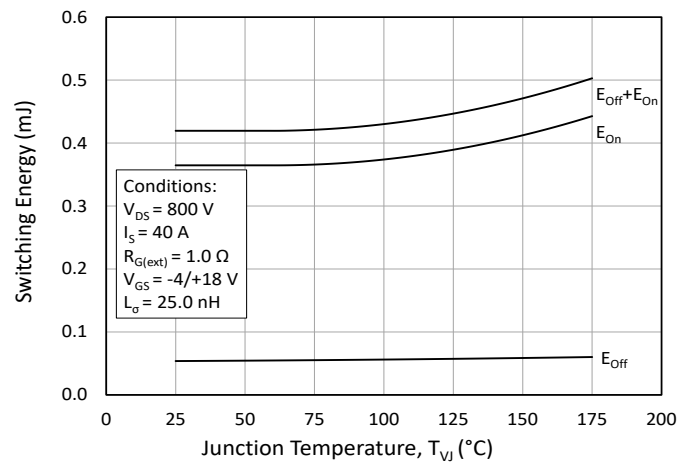


Figure 26. Clamped Inductive Switching Energy vs. Temperature

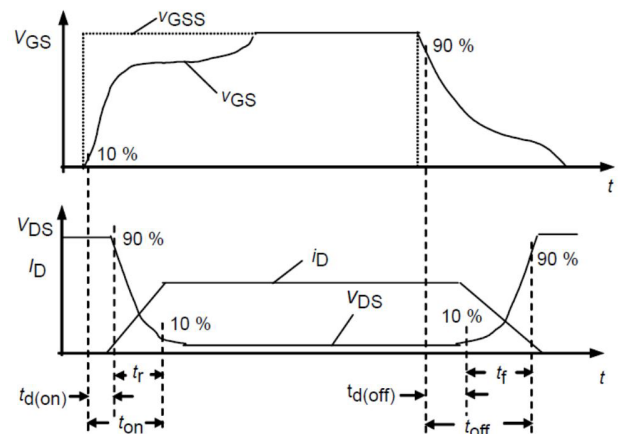


Figure 28. Switching Times Definition

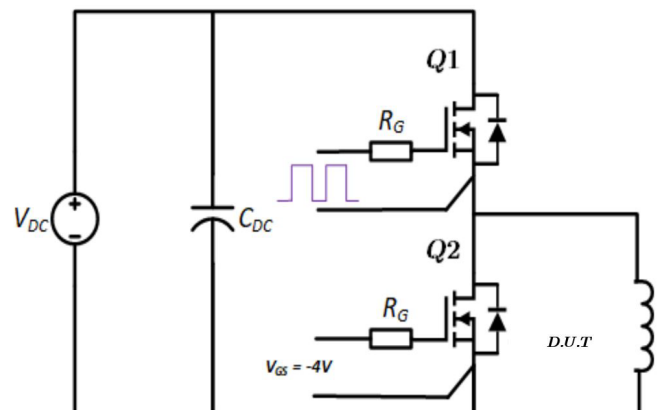
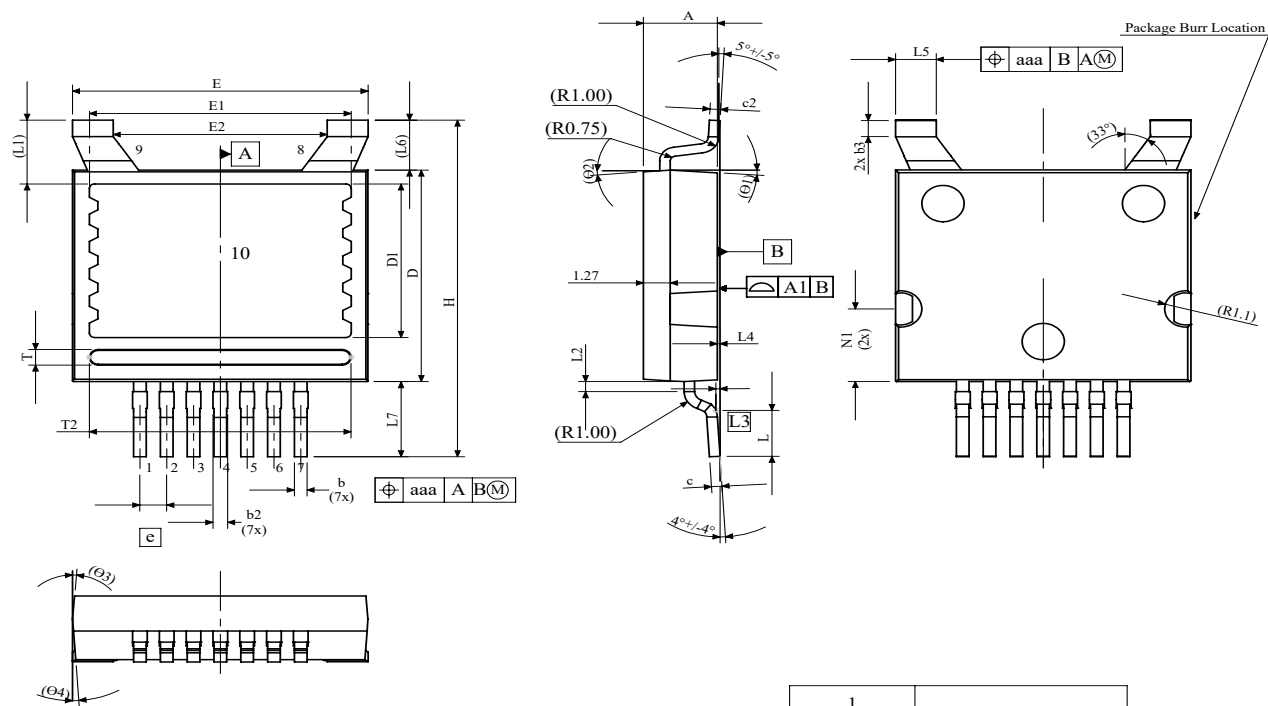


Figure 30. Clamped Inductive Body diode Switching Waveform Test Circuit

Package Dimensions



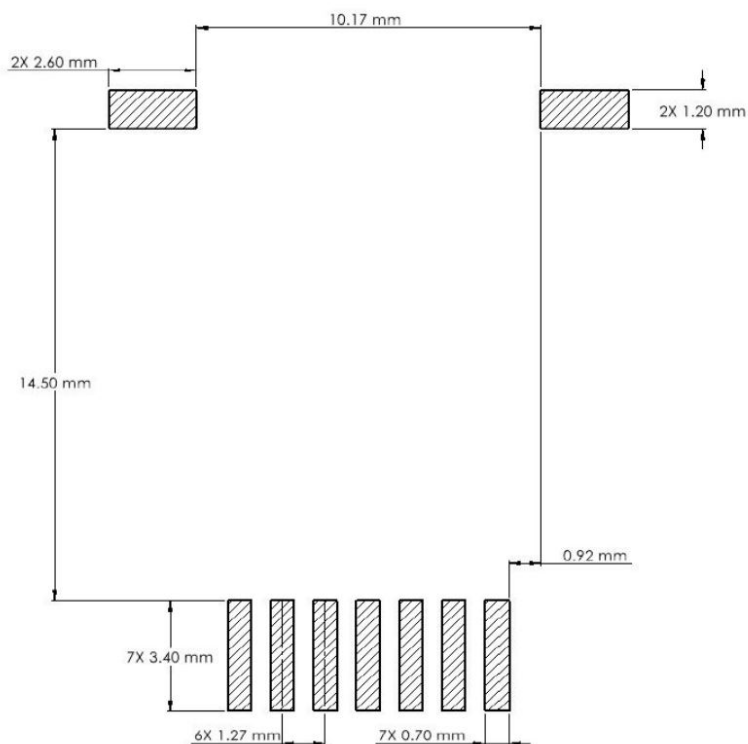
SYMBOL	MIN (mm)	MAX (mm)
A	3.40	3.60
A1	---	0.05
b	0.50	0.70
b2	0.50	1.00
b3	0.85	1.05
c	0.40	0.60
e2	0.40	0.60
D	11.55	11.75
D1	8.30	8.50
E	13.92	14.12
E1	12.22	12.42
E2	9.92	10.22
e	BSC 1.27	
H	18.00	19.00
L	2.47	2.67
L1	BSC 3.51	
L2	0.3	0.73
L3	BSC 0.26	
L4	0.09	0.2
L5	1.83	2.13
L6	BSC 2.75	
L7	4.03	4.23
T	0.75	0.95
T2	12.30	12.50
N1	3.90	4.10
Θ1	0°	8°
Θ2	0°	8°
Θ3	0°	8°
Θ4	0°	8°
aaa	---	0.10

1	SOURCE
2	
3	
4	
5	DRIVER SOURCE
6	
7	GATE
8	DRAIN
9	DRAIN
10	DRAIN

- NOTE
1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
  2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
  3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
  4. PACKAGE BURR FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS

## Recommended Solder Pad Layout

All dimensions in mm



**Revision history**

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Document Version	Date of release	Description of changes
1	October 2025	Initial release



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### Contact info:

4600 Silicon Drive  
Durham, NC 27703 USA  
Tel: +1.919.313.5300  
[www.wolfspeed.com/power](http://www.wolfspeed.com/power)

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